

**PATENT ASSIGNMENT**

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
Name	Execution Date
Mayank Kumar SINGH	09/05/2011
Daljeet KUMAR	09/05/2011
Hiten ADVANI	09/05/2011
<b>RECEIVING PARTY DATA</b>	
Name:	STMicroelectronics Pvt. Ltd.
Street Address:	Plot N. 1, Knowledge Park III
City:	Greater NOIDA
State/Country:	INDIA
Postal Code:	201308
<b>PROPERTY NUMBERS Total: 1</b>	
Property Type	Number
Application Number:	13218134
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ATTORNEY DOCKET NUMBER:	2415-049-03
NAME OF SUBMITTER:	Bryan A. Santarelli
Total Attachments: 3 source=2415-049-03_Assigmment#page1.tif source=2415-049-03_Assigmment#page2.tif source=2415-049-03_Assigmment#page3.tif	

OP \$40.00 13218134

## ASSIGNMENT

WHEREAS we, Mayank Kumar SINGH; Daljeet KUMAR; and Hiten ADVANI (hereinafter "ASSIGNORS"), having mailing addresses of MD1 418-B/67, Sector – D1, LDA Colony, Kanpur Road, Lucknow 226012, India; J-1/245, DDA Flats, Kalka Ji, New Delhi 110019, India; and C-295, Sarita Vihar, New Delhi, India, respectively, are the joint inventors of the invention(s) disclosed in an application for United States letters patent entitled, **IMPEDANCE CALIBRATION CIRCUIT AND METHOD**, filed August 25, 2011, and allotted United States Patent Application No. 13/218,134 (an attorney for the assignee may enter this information after this Assignment is executed); and

WHEREAS, STMicroelectronics Pvt. Ltd. (hereinafter "ASSIGNEE"), a juristic entity of the State of India, having a principle place of business at Plot N. 1, Knowledge Park III, Greater NOIDA 201308 – Uttar Pradesh, India, is desirous of acquiring the entire right, title, and interest in and to the invention(s), application(s), and/or any letters patent(s) that may be granted therefor in the United States and in any and all foreign countries;


NOW, THEREFORE, in exchange for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNORS hereby sell, assign, and transfer unto said ASSIGNEES the entire right, title, and interest in and to said invention(s), said application(s), including any and all nonprovisional application(s) for letters patent claiming priority thereto, and any and all letters patent(s) which may be granted therefor in the United States of America and its territorial possessions and in any and all foreign countries, and in any and all divisional, reissue, continuation, continuation-in-part, and substitute application(s) thereof, including the right to file any foreign application(s) directly in the name of ASSIGNEES and to claim priority rights deriving from said United States application(s) to which said foreign application(s) are entitled by virtue of international convention, treaty, or otherwise, said invention(s), application(s) and any and all letters patent(s) granted therefor to be held and enjoyed by ASSIGNEES, their successors, and assigns as fully and entirely as same would have been held and enjoyed by ASSIGNORS had this assignment, transfer, and sale not been made;

ASSIGNORS hereby authorize and request the Director of the United States Patent and Trademark Office to issue any and all letters patent(s) on said invention(s) to ASSIGNEES;

ASSIGNORS hereby covenant that no assignment, sale, agreement, or encumbrance has been or will be made which would conflict with this assignment;

ASSIGNORS further transfer and assign to ASSIGNEES all causes of action, rights, and remedies arising under any such application(s) for United States and/or foreign letters patent(s) on said invention(s) prior to or after the effective date of this Assignment; and

ASSIGNORS agree to execute all instruments and documents required for the making and prosecution of applications for any and all application(s) for United States and/or foreign letters patent(s) on said invention(s), for litigation regarding any and all application(s) and/or letters patent(s), and/or for the purpose of protecting title to said invention(s), application(s), and/or letters patent(s) therefor.



\_\_\_\_\_  
Mayank Kumar SINGH

5/9/2011

\_\_\_\_\_  
DATE

I hereby declare that I was personally present and did see ASSIGNOR, who is personally known to me to be the person named above, duly sign and execute this Assignment document on this 5<sup>th</sup> day of SEPTEMBER, 2011, of his/her own free will for the purpose expressed therein at the following location:

ST MICROELECTRONICS INDIA

WITNESS

Name: Surendra Kumar

Signature: 

Daljeet

05/09/2011

\_\_\_\_\_  
Daljeet KUMAR

\_\_\_\_\_  
DATE

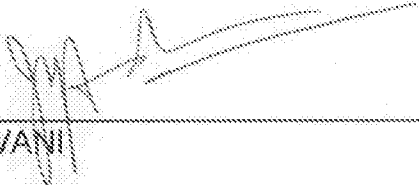
I hereby declare that I was personally present and did see ASSIGNOR, who is personally known to me to be the person named above, duly sign and execute this Assignment document on this 5<sup>th</sup> day of SEPTEMBER, 2011, of his/her own free will for the purpose expressed therein at the following location:

ST MICROELECTRONICS, INDIA

WITNESS

Name: Surendra Kumar

Signature: 



\_\_\_\_\_  
Hiten ADVANI

5/9/11  
\_\_\_\_\_  
DATE

I hereby declare that I was personally present and did see ASSIGNOR, who is personally known to me to be the person named above, duly sign and execute this Assignment document on this 5<sup>th</sup> day of SEPTEMBER, 2011, of his/her own free will for the purpose expressed therein at the following location:

ST MICROELECTRONICS, INDIA

WITNESS

Name: Surendra Kumar

Signature: 